



#### **N-CHANNEL ENHANCEMENT MODE MOSFET**

## **Product Summary**

BVDSS	Rds(on)	I <sub>D</sub> T <sub>A</sub> = +25°C
240)/	11Ω @ V <sub>GS</sub> = 10V	0.27A
240V	12Ω @ V <sub>GS</sub> = 4.5V	0.26A

## **Description**

This new generation MOSFET has been designed to minimize the onstate resistance (RDS(ON)) yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

## **Applications**

- DC-DC converters
- Power-management functions
- Battery-operated systems and solid-state relays
- Drivers: relays, solenoids, lamps, hammers, displays, memories, transistors, etc.

#### **Features and Benefits**

- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Small Surface Mount Package
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.

https://www.diodes.com/quality/product-definitions/

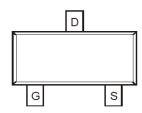
 An automotive-compliant part is available under separate datasheet (<u>DMN24H11DSQ</u>)

### **Mechanical Data**

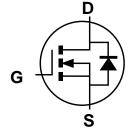
- Package: SOT23
- Package Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Solderable per MIL-STD-202, Method 208
   Lead Free Plating (Matte Tin Finish Annealed over Alloy 42
   Leadframe). (3)
- Terminal Connections: See Diagram
- Weight: 0.006 grams (Approximate)







Top View Pin Configuration



**Equivalent Circuit** 

# **Ordering Information** (Note 4)

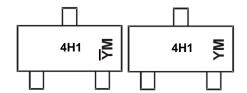
Part Number	Pankago	Packing		
Fait Number	Package	Qty.	Carrier	
DMN24H11DS-7	SOT23	3,000	Tape & Reel	
DMN24H11DS-13	SOT23	10,000	Tape & Reel	

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/



# **Marking Information**



4H1 = Product Type Marking Code

YM = Date Code Marking for SAT (Shanghai Assembly/ Test Site)
YM = Date Code Marking for CAT (Chengdu Assembly/ Test Site)
Y or Y = Year (ex: K = 2023)
M = Month (ex: 9 = September)

Date Code Key

Year	2014	-	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032
Code	В	-	K	L	М	N	Р	R	S	Т	U	V
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

## **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	VDSS	240	V	
Gate-Source Voltage		Vgss	±20	V
Continuous Drain Current (Note 6) V <sub>GS</sub> = 10V	lD	0.27 0.22	А	
Pulsed Drain Current (10µs Pulse, Duty Cycle ≦1%)	I <sub>DM</sub>	0.8	Α	
Maximum Body Diode Continuous Current (Note 6)	Is	0.27	А	
Peak Diode Recovery dv/dt		dv/dt	6.0	V/ns

## Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Total Dawar Dissination	(Note 5)	Б	0.75	W	
Total Power Dissipation	(Note 6)	P <sub>D</sub>	1.2	VV	
Thormal Bosistanes, Jungtion to Ambient	(Note 5)	Dov	166		
Thermal Resistance, Junction to Ambient	(Note 6)	Reja	104	°C/W	
Thermal Resistance, Junction to Case	(Note 6)	R <sub>0</sub> JC	35		
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C	

Notes:

- 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper pad layout.



# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

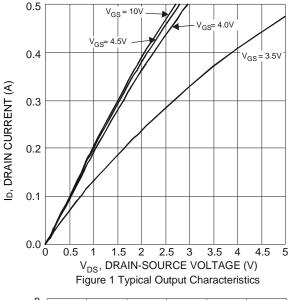
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BVDSS	240	_		<b>V</b>	$V_{GS} = 0V, I_{D} = 250\mu A$
Zero Gate Voltage Drain Current	IDSS	_	_	100	nA	V <sub>DS</sub> = 240V, V <sub>GS</sub> = 0V
Gate-Body Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	1.0	2.0	3.0	<b>V</b>	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$
Static Drain-Source On-Resistance	Descour	_	3.7	11	Ω	$V_{GS} = 10V, I_D = 0.3A$
Static Dialif-Source Off-Nesistance	RDS(ON)	_	4.0	12	12	$V_{GS} = 4.5V, I_D = 0.2A$
Diode Forward Voltage	VsD	_	0.7	1.2	٧	V <sub>G</sub> S = 0V, I <sub>S</sub> = 0.1A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	Ciss	_	76.8	_		V 05V V 0V
Output Capacitance	Coss	_	6.9	_	pF	$V_{DS} = 25V, V_{GS} = 0V,$ f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	4.1	_		1 - 1.0WH12
Gate Resistance	Rg	_	17	_	Ω	V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1.0MHz
Total Gate Charge	Qg	_	3.7	_		
Gate-Source Charge	Qgs	_	0.3	_	nC	$V_{DS} = 192V, V_{GS} = 10V,$ $I_{D} = 0.1A$
Gate-Drain Charge	Qgd	_	2.1	_		ID = 0.1A
Turn-On Delay Time	t <sub>D(on)</sub>	_	4.8	_		
Turn-On Rise Time	tr	_	4.7	_		V <sub>DS</sub> = 120V, I <sub>D</sub> = 0.1A,
Turn-Off Delay Time	t <sub>D(off)</sub>		17.5		ns	$V_{GS} = 10V$ , $R_G = 6.0\Omega$
Turn-Off Fall Time	tf	_	102.3	_		
Reverse Recovery Time	t <sub>rr</sub>	_	45.6	_	ns	V <sub>R</sub> = 100V, I <sub>F</sub> = 1.0A,
Reverse Recovery Charge	Q <sub>rr</sub>	_	51.6		nC	di/dt = 100A/µs

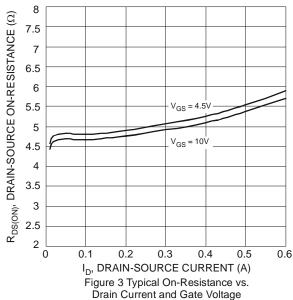
Notes:

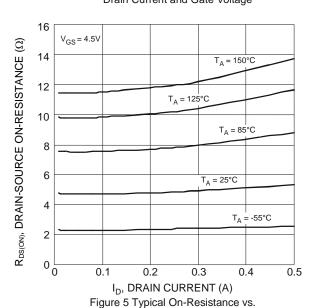
<sup>7.</sup> Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to production testing.



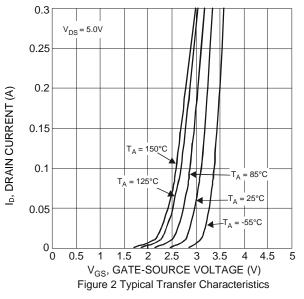


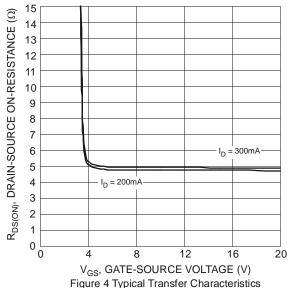






Drain Current and Temperature





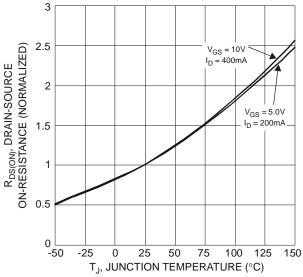
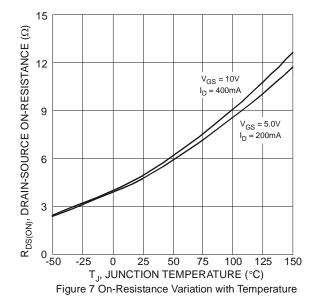
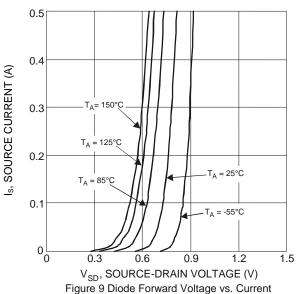


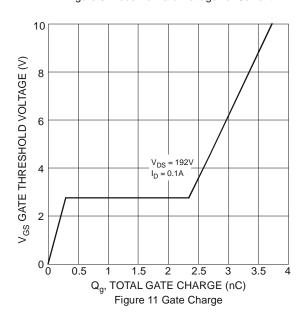
Figure 6 On-Resistance Variation with Temperature











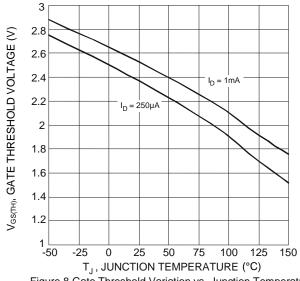
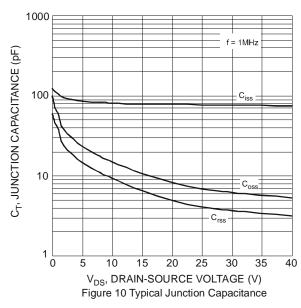
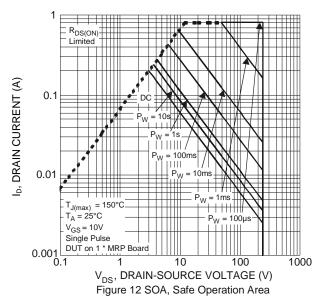
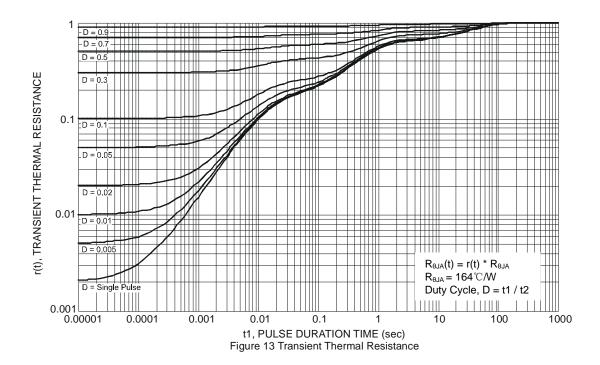


Figure 8 Gate Threshold Variation vs. Junction Temperature







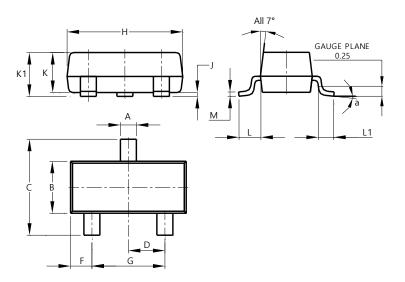




# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### SOT23

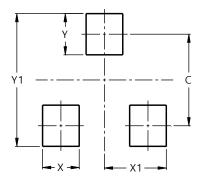


SOT23							
Dim	Min	Max	Тур				
Α	0.37	0.51	0.40				
В	1.20	1.40	1.30				
С	2.30	2.50	2.40				
D	0.89	1.03	0.915				
F	0.45	0.60	0.535				
G	1.78	2.05	1.83				
Η	2.80	3.00	2.90				
J	0.013	0.10	0.05				
K	0.890	1.00	0.975				
<b>K</b> 1	0.903	1.10	1.025				
L	0.45	0.61	0.55				
L1	0.25	0.55	0.40				
М	0.085	0.150	0.110				
а	0°	8°					
All	Dimens	ions in	mm				

# Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### SOT23



Dimensions	Value (in mm)
С	2.0
Х	0.8
X1	1.35
Υ	0.9
Y1	29



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